nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

| Supplier Nexperia B.V. | | User Part Number | | | | | | |
|---|----------------------------------|--|-------------|-----------|------------|-----------|--|--|
| | | PMEG3005ELS-Q | | | | | | |
| Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test | | Part Description | | | | | | |
| | | Nexperia DHAM Schottky | | | | | | |
| | | MCD package | | | | | | |
| | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | | |
| | TEST | | | | , | | | |
| | Pre- and Post-Stress | | | | | | | |
| # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | |
| | | JESD22-A113 | ,,,, | | un purco | | | |
| | | Bake Tamb = $125 ^{\circ}\text{C}$ | 24 hours | | | | | |
| | PC | Soak Tamb = 85 °C, RH = 85% | 168 hours | | | | | |
| # A1 | Preconditioning | Reflow soldering | 3 cycles | 208 | 9760 | 0 | | |
| | | MIL-STD-750-1 | | | | | | |
| | HTRB | M1038 Method A | | | | | | |
| | | Tj = Tjmax, Vr = 100% of max. datasheet | | | | | | |
| # B1 | Bias | reverse voltage ^[1] | 1000 hours | 206 | 9320 | 0 | | |
| | | | 1000 110010 | 200 | 5520 | 0 | | |
| | тс | JESD22-A104 | | | | | | |
| # A4 | Temperature Cycling | -65 °C to Timax, not to exceed 150°C | 1000 cycles | 53 | 2400 | 0 | | |
| | | | 1000 07000 | 00 | 2.00 | 0 | | |
| | UHAST | JESD22-A118 | | | | | | |
| # A3 or | Unbiased HAST | Tamb = 130 °C, RH = 85 % | | | | | | |
| | | JESD22-A102 | —96 hours | 53 | 2400 | 0 | | |
| | AC | Tamb = $121 ^{\circ}$ C, RH = $100 ^{\circ}$ | | | | | | |
| # A3 alt | Autoclave | Pressure = $205 \text{ kPa} (29.7 \text{ psia})$ | | | | | | |
| # AS dit | Autociave | | | | | | | |
| | H3TRB | JESD22-A101 | | | | | | |
| | High Humidity High | Tamb = $85 ^{\circ}$ C, RH = 85% , VR = 80% of | | | | | | |
| # A2 alt | Temperature Reverse Bias | | 1000 hours | 53 | 2400 | 0 | | |
| # A2 alt | remperature reverse blas | | 1000 1100/5 | 55 | 2400 | U | | |
| | IOL | MIL-STD-750 Method 1037 | | | | | | |
| # A5 | | ton = toff, devices powered to insure ΔTj = | 1000 hours | 40 | 2560 | 0 | | |
| # A5 | Intermittent Operating Life | 100 °C 101 15000 Cycles | 1000 hours | 49 | 2560 | 0 | | |
| | BGU | 150000 4111 | | | | | | |
| # 60 | RSH Desistance to Colder Uset | JESD22-A111 | 10 - | | | | | |
| # C8 | Resistance to Solder Heat | 260 °C ± 5 °C | 10 s | n.a. | n.a. | n.a. | | |
| | SD | 1 070 000 | | | | | | |
| # C10 | Solderability | J-STD-002 | | 37 | 1110 | 0 | | |

The physical limitations of Schottky diodes have to be considered (thermal runaway).
The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| - | | | | | | | | |
|---|-----------|------------|----------|---------|--------------------|------------|--|--|
| v | Vafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) | | |
| N | lexperia | | | | | | | |
| D | DHAM | Schottky | 9320 | 0 | 0,46 | 2,19E+09 | | |

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